

2SJ669

Relay Drive, DC/DC Converter and Motor Drive Applications

- 4-V gate drive
- Low drain-source ON-resistance: $R_{DS(ON)} = 0.12 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.0 S$ (typ.)
- Low leakage current: $I_{DSS} = -100 \mu A$ (max) ($V_{DS} = -60 V$)
- Enhancement mode: $V_{th} = -0.8$ to $-2.0 V$
($V_{DS} = -10 V, I_D = -1 mA$)

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristic	Symbol	Rating	Unit	
Drain-source voltage	V_{DSS}	-60	V	
Drain-gate voltage ($R_{GS} = 20 k\Omega$)	V_{DGR}	-60	V	
Gate-source voltage	V_{GSS}	± 20	V	
Drain current	DC (Note 1)	I_D	-5	A
	Pulse (Note 1)	I_{DP}	-20	A
Drain power dissipation	P_D	1.2	W	
Single-pulse avalanche energy (Note 2)	E_{AS}	40.5	mJ	
Avalanche current	I_{AR}	-5	A	
Repetitive avalanche energy (Note 3)	E_{AR}	0.12	mJ	
Channel temperature	T_{ch}	150	$^\circ C$	
Storage temperature range	T_{stg}	-55~150	$^\circ C$	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to ambient	$R_{th(ch-a)}$	104	$^\circ C / W$

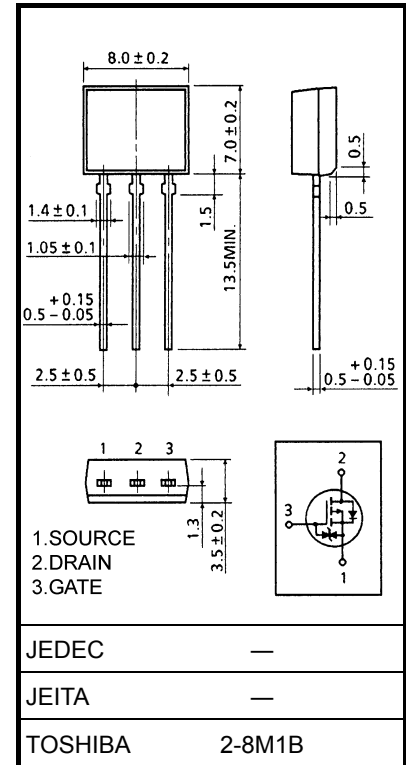
Note 1: The channel temperature should not exceed $150^\circ C$ during use.

Note 2: $V_{DD} = -25 V, T_{ch} = 25^\circ C$ (initial), $L = 2.2 mH, R_G = 25 \Omega, I_{AR} = -5 A$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.

Unit: mm



Weight: 0.54 g (typ.)

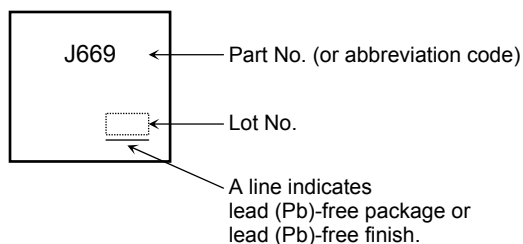
Electrical Characteristics (Ta = 25°C)

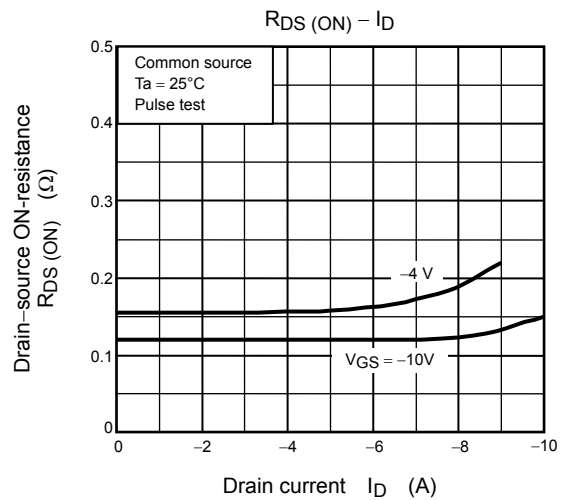
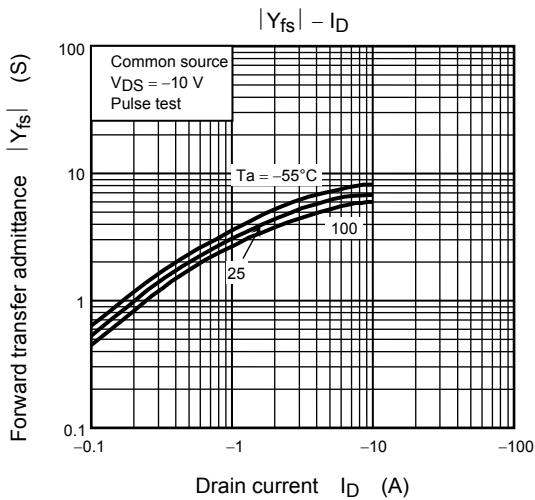
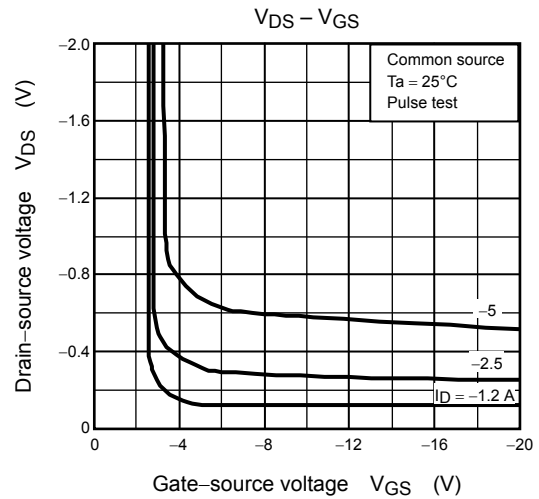
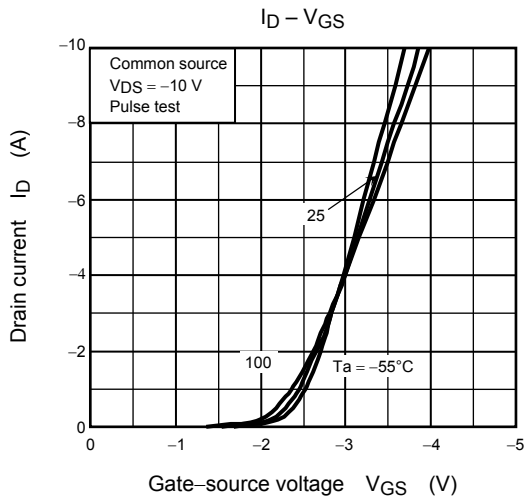
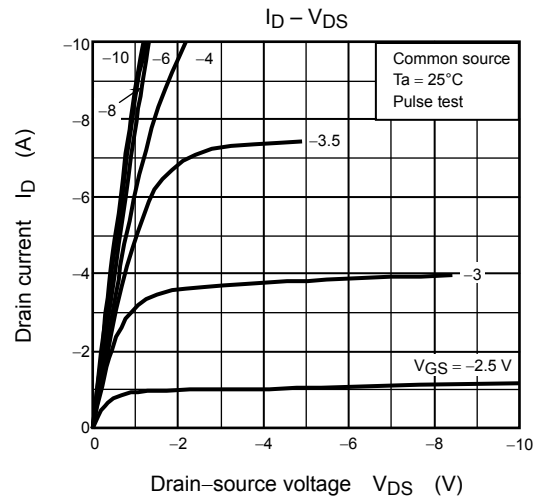
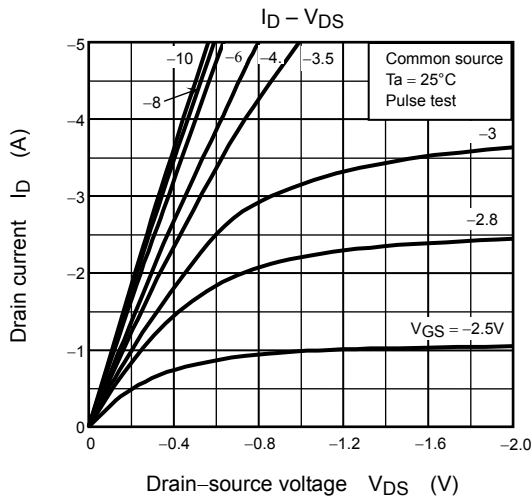
Characteristic		Symbol	Test Condition	Min	Typ.	Max	Unit
Gate leakage current		I_{GSS}	$V_{GS} = \pm 16\text{ V}, V_{DS} = 0\text{ V}$	—	—	± 10	μA
Drain cutoff current		I_{DSS}	$V_{DS} = -60\text{ V}, V_{GS} = 0\text{ V}$	—	—	-100	μA
Drain-source breakdown voltage		$V_{(BR)DSS}$	$I_D = -10\text{ mA}, V_{GS} = 0\text{ V}$	-60	—	—	V
		$V_{(BR)DSX}$	$I_D = -10\text{ mA}, V_{GS} = 20\text{ V}$	-35	—	—	V
Gate threshold voltage		V_{th}	$V_{DS} = -10\text{ V}, I_D = -1\text{ mA}$	-0.8	—	-2.0	V
Drain-source ON-resistance		$R_{DS(ON)}$	$V_{GS} = -4\text{ V}, I_D = -2.5\text{ A}$	—	0.16	0.25	Ω
			$V_{GS} = -10\text{ V}, I_D = -2.5\text{ A}$	—	0.12	0.17	
Forward transfer admittance		$ Y_{fs} $	$V_{DS} = -10\text{ V}, I_D = -2.5\text{ A}$	2.5	5.0	—	S
Input capacitance		C_{iss}	$V_{DS} = -10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	—	700	—	pF
Reverse transfer capacitance		C_{rss}		—	60	—	
Output capacitance		C_{oss}		—	90	—	
Switching time	Rise time	t_r		—	14	—	ns
	Turn-on time	t_{on}		—	24	—	
	Fall time	t_f		—	14	—	
	Turn-off time	t_{off}		—	95	—	
Total gate charge (gate-source plus gate-drain)		Q_g	$V_{DD} \approx -48\text{ V}, V_{GS} = -10\text{ V}, I_D = -5\text{ A}$	—	15	—	nC
Gate-source charge		Q_{gs}		—	11	—	
Gate-drain ("Miller") charge		Q_{gd}		—	4	—	

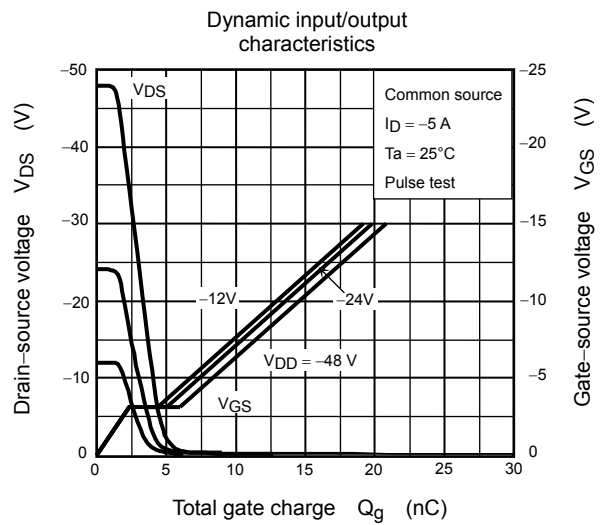
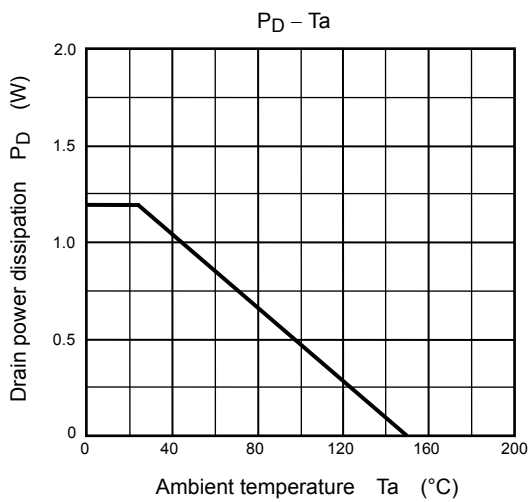
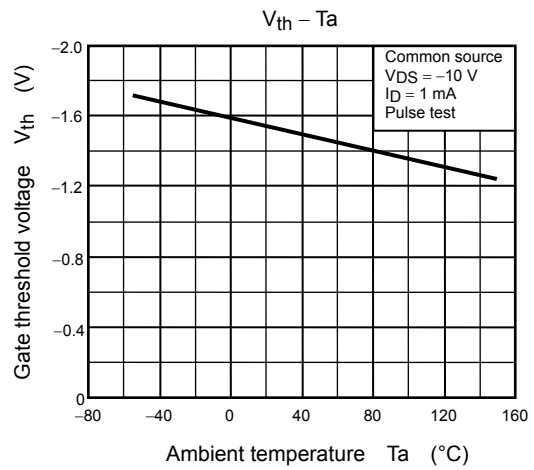
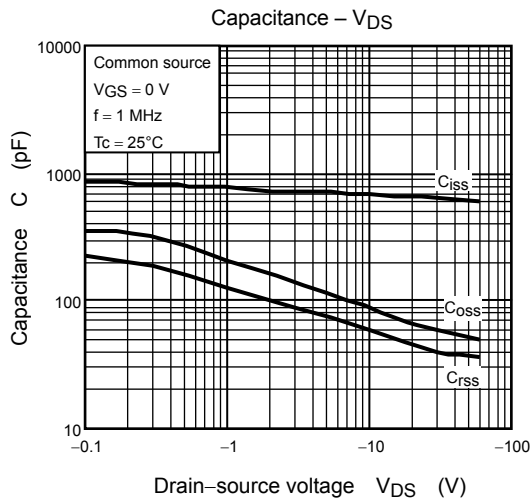
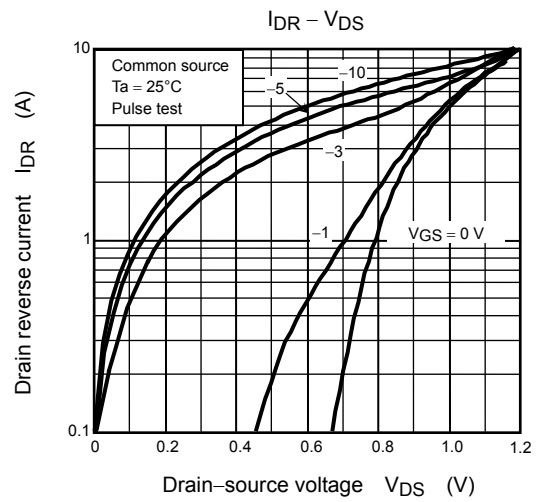
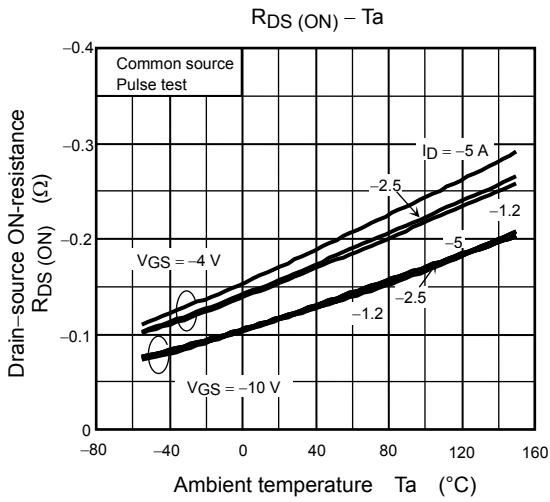
Source-Drain Ratings and Characteristics (Ta = 25°C)

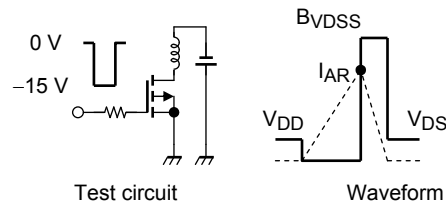
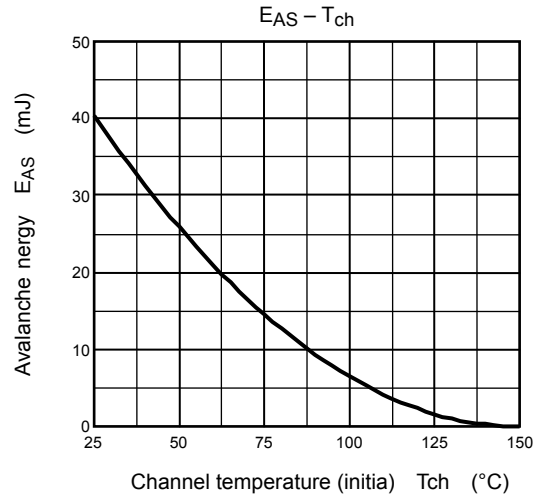
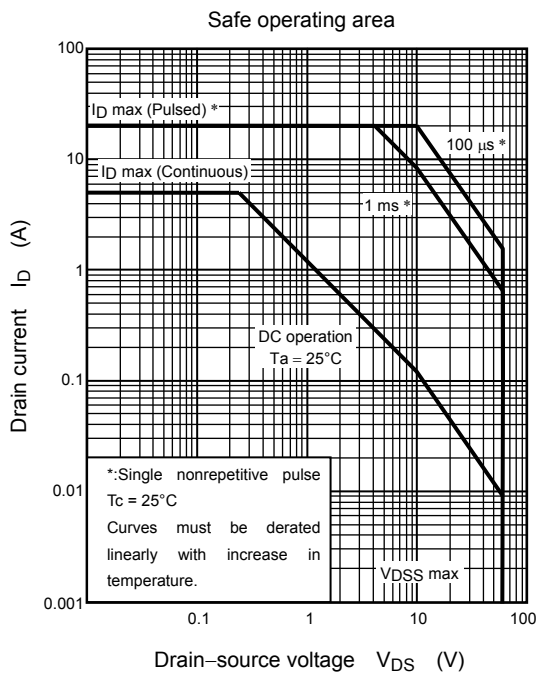
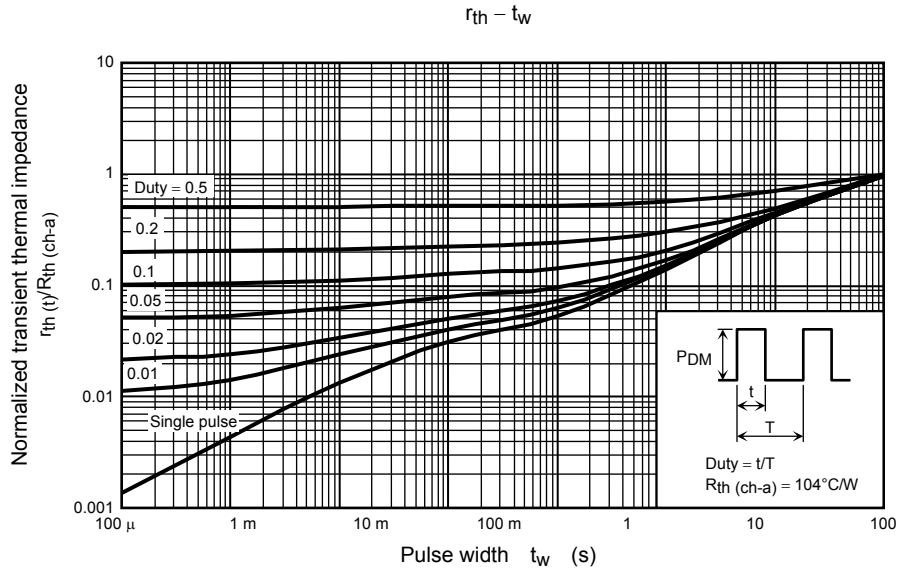
Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I_{DR}	—	—	—	-5	A
Pulse drain reverse current (Note 1)	I_{DRP}	—	—	—	-20	A
Forward voltage (diode)	V_{DSF}	$I_{DR} = -5\text{ A}, V_{GS} = 0\text{ V}$	—	—	1.7	V
Reverse recovery time	t_{rr}	$I_{DR} = -5\text{ A}, V_{GS} = 0\text{ V}$	—	40	—	ns
Reverse recovery charge	Q_{rr}	$dI_{DR} / dt = 50\text{ A} / \mu\text{S}$	—	32	—	nC

Marking









$R_G = 25 \Omega$
 $V_{DD} = -25 V, L = 2.2 mH$

$$E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS - V_{DD}} \right)$$

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